DESCRIPTION

The fundamental of SP6052 synchronous rectifier (SR) driver IC is based on our U.S. patented methods that utilize the principle of "prediction" logic circuit. The IC deliberates previous cycle timing to control the SR in present cycle by "predictive" algorithm that makes adjustments to the turn-off time, in order to achieve maximum efficiency and avoid cross-conduction at the same time. SP6052 is especially suitable for Forward and DC/DC Module.

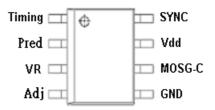
APPLICATIONS

- Storage area network power supplies
- Servers & workstations
- Embedded systems
- Industrial & commercial systems using high current processors
- Telecommunication converters
- DC/DC Power Module

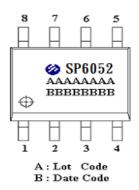
FEATURES

- Offers efficiency improvement over Schottky Diode (depends on drive configuration of the SR).
- Drives all Power MOSFET
- Prediction gate timing control.
- Minimum MOSFET body diode conduction.
- Operating at high switching frequency 500Khz.
- Synchronize to transformer secondary voltage waveform.
- Linear setting of timing function.
- Minimum VDS pulse masking function
- Bi-directional rapid load protection function.
- Self-detecting DCM / CCM to enhance the performance under the variable switching frequency condition.
- SOP-8 Package

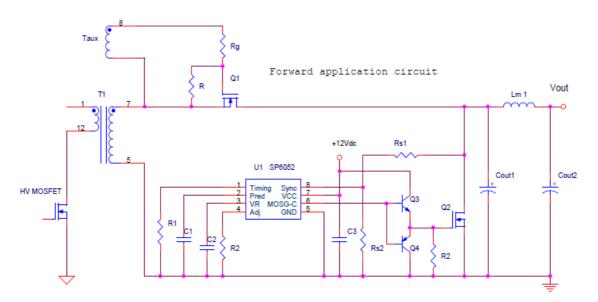
PIN CONFIGURATION (SOP-8)



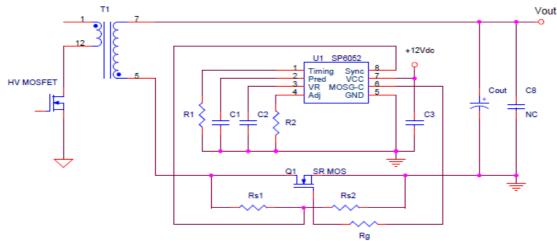
PART MARKING



TYPICAL APPLCATION CIRCUIT



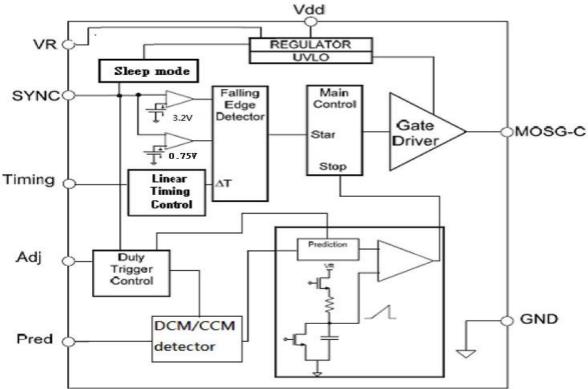
Flyback application circuit



PIN DESCRIPTION

Pin	Symbol	Description
1	Timing	Discontinuous current filter timing adjustment resistor connection.
2	Pred	Capacitor to store previous cycle timing for SR MOSFET.
3	VR	Voltage Regulator.
4	Adj	Trigger point adjustment for Dynamic state.
5	GND	Ground connection.
6	MOSG-C	Catch MOSFET gate drive.
7	Vdd	DC supply voltage.
8	SYNC	Synchronized signal from the VDS of SR MOSFET.

BLOCK DIAGRAM



ORDERING INFORMATION

Part Number	Package	Part Marking
SP6052S8RGB	SOP-8	SP6052

※ SP6052S8RGB : Tape Reel ; Pb – Free ; Halogen - Free

ABSOULTE MAXIMUM RATINGS (TA=25°C, unless otherwise specified.)

The following ratings designate persistent limits beyond which damage to the device may occur.

Symbol	Parameter	Value	Unit
Vdd	DC Supply Voltage	16	V
I _{OUT}	Peak Source Current (Pulsed)	2.0	A
1001	Peak Sink Current (Pulsed)	2.0	А
PD	Power Dissipation @ TA=85°C(*)	0.25	W
TJ	Operating Junction Temperature Range	-40 to 150	°C
TSTG	Storage Temperature Range	-40 to 150	°C
TLEAD	Lead Soldering Temperature for 5 sec.	260	°C

THERMAL RESISTANCE

Symbol	Parameter	Value	Unit			
Roja	Thermal Resistance Junction to Ambient (*)	150	°C/W			
(*) The power dissipation and thermal resistance are evaluated under copper board mounted with free air conditions.						

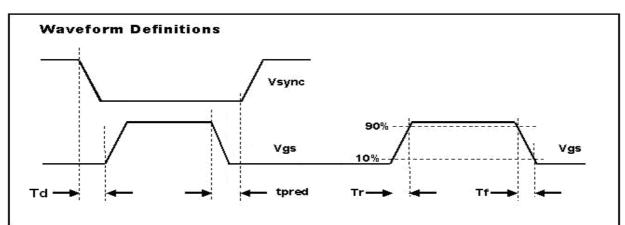
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ELECTRICAL CHARACTERISTICS

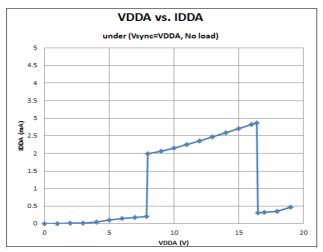
(TA=25°C, Vdd=12V, Freq. =50 KHz, Duty Cycle=50%, unless otherwise specified.)

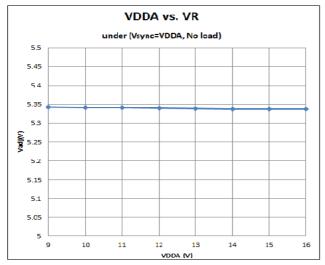
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
SUPPLY IN	PUT	1			4	-
Idd	Sumply sumont	Sleep mode		0.2		mA
IDD	Supply current	V _{SYNC} =0V, Vdd on, No load	1.7	2.3	3.1	
Vdd	Supply voltage	Idd peak < 2A			16	V
Vdd on	Enable voltage		7.6	8.0	8.4	V
Vdd hysteresis	Enable voltage			0.25	0.5	V
Vovp	Over voltage protection		16	16.5	17	V
Vovp hystersis				0.35		V
SYNC REFI	ERENCE (SYNC)					
Vshth	SYNC high threshold			3.2		V
Vslth	SYNC low threshold			0.75		V
Vsync	SYNC wake-up voltage	Isync=3mA	6	6.7	7	V
Isync Voltage Reg	SYNC input current alator REFERENCE (VR				3	mA
VR	voltage		5.2		5.4	V
Ivr	VR Output Current				50	mA
ON TIME D	UTY SETUP (PIN 6)	1			4	-
Ton-time				40		uS
MOSFET G	ATE DRIVER (MOSG-C					
Voh	Output high voltage	Io=-200mA	10.3	11.0		V
Vol	Output low voltage	Io=200mA		0.5	0.8	V
Td	Propagation delay	No load	25	50	155	nS
Tpred		No load		200		nS
Tr	Rise time	Load = 1nF(*)		11	25	nS
Tf	Fall time	Load = 1nF(*)		13	25	nS
Dynamic Pro						
Dt_CCM	Dynamic variable	Pin 4, 25K Ω to GND		500		nS
Dt_DCM	Dynamic variable	Pin 4, 25K Ω to GND		1500		nS
Ton-min	MOSG-C on time	PWM adjusts time > Dt	0.4	0.6	0.8	uS

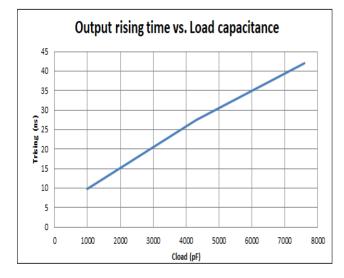
(*) Tr & Tf are measured among 10% and 90% of starting and final voltage.

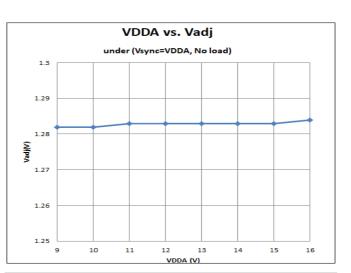


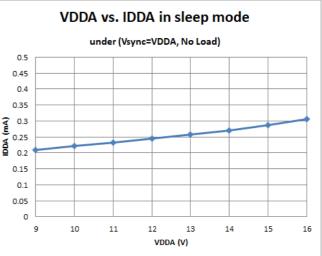
TYPICAL CHARACTERISTICS

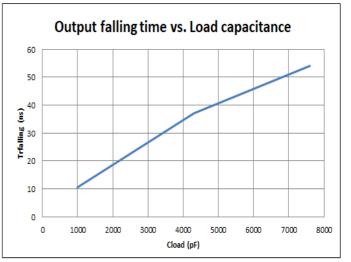






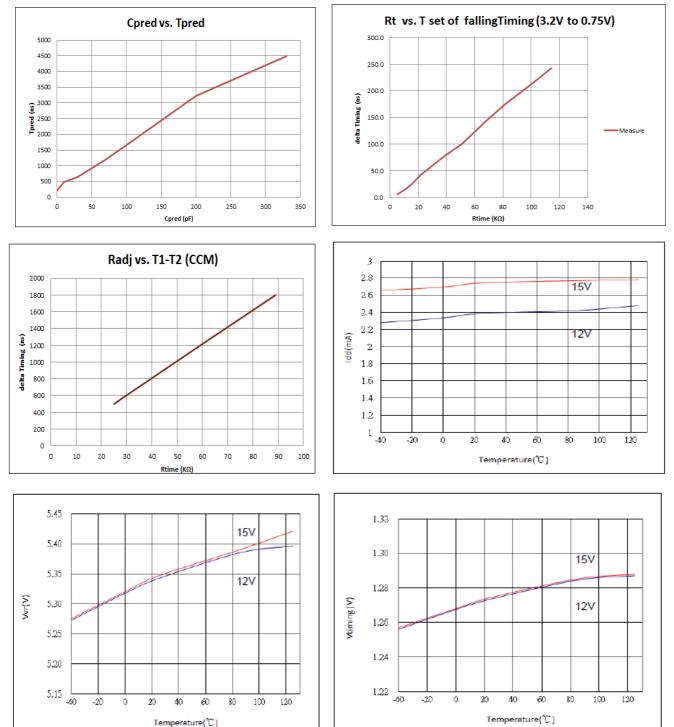






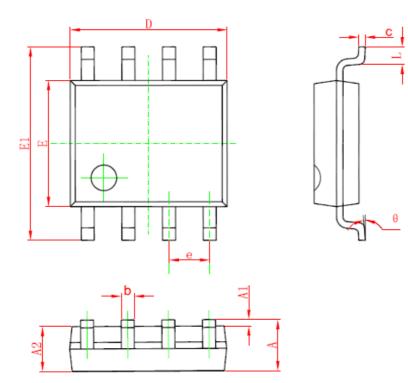
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TYPICAL CHARACTERISTICS





SOP-8 PACKAGE OUTLINE



Constant	Dimensions In Millimeters		Dimensions In Inches	
Symbol	Min	Max	Min	Max
A	1.350	1. 750	0.053	0.069
A1	0. 100	0. 250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0. 330	0. 510	0.013	0.020
с	0. 170	0. 250	0.006	0.010
D	4. 700	5.100	0.185	0.200
E	3.800	4.000	0.150	0. 157
E1	5.800	6. 200	0. 228	0. 244
е	1. 270 (BSC)		0.050 (BSC)	
L	0. 400	1. 270	0.016	0.050
θ	0°	8°	0°	8°

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